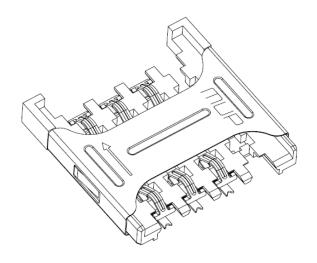


# SAMPLE APPROVAL

Model No:MUP-C790

Revision:1.0

Issue Date:May.10.2011





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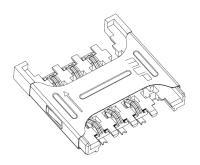
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#### 1 · INTRODUSTION

#### General

The C790 instrict accordance with ETSI TS 102 221 internationally recognized standard.It is designed for high performance and flexibility to give prospective customers a quick and perfect applications of the individual devices in their series products. Other kinds of models are optional.your need is our goal



#### **Features**

- Fast reaction capacity.
- Broad application domain.
- Ideal stable performance.
- The superior performance.
- ETSI TS 102 221 Standard Micro SIM Card.(note)

#### **Applications**

- **Access Control Terminals.**
- **Terminal Identification Module.**
- Telecommunication.
- Handest
- Grasps pos machine
- Memory dense spoon management special-purpose
- Other Identification recognition.

## **MILP** Micro SIM Card Connector MUP-C790

#### 2 · TECHNICAL CHARACTERISTICS

#### 2.1 General Characteristics

No	Items	Standard	Descriptions	
1	Dimensions		13.40L×13.40W×2.40H mm	
2	Weight		Approx.0.50g	
3	Card Size	ETSI.TS.102.221	15.00×12.00×0.76mm	
4	Contact pringciple		Friction technology	
5	Durability		5000 cycles Min	
6	Mounting Type		SMT (without post)	
Mate	Material:			
1	Insulator		Themoplastic UL94V-0	
2	Data Contact		Phosphor bronze	
3	Cover		SUS(304)	
4	Plating		Gold over Nickel	

#### 2.2 Electrical Characteristics : According to Standard IEC512

#### 2.2.1 Data Contacts

No	Items	Standard	Descriptions	
1	Number of Contacts		6Pins	
2	Contact highly		0.70+0.15/-0.10mm	
3	Rated voltage		50V max	
4	Rated current		1A max,10μ A min	
5	Contact resistance	IEC512-2-2a	50mΩ typical,100 mΩ max	
6	Insulation resistance pin to pin	IEC512-2-3a	>1000 MΩ /500 VDC	
7	Dielectric withstanding voltage	IEC512-2-4a	500V AC rms 1Min(sea level)	



## **MILP** Micro SIM Card Connector MUP-C790

#### 2.3 Mechanical Characteristics.

No	Items	Standard	Descriptions
1	Contact force		0.5N Min.
2	Contact Location	ETSI.TS.102.221	

#### 2.4 Solder ability.

No	Items	Standard	Descriptions	
1	Wave	IEC-68-2-20	Not applicable	
2	Vaporphase		215℃,30sec.Max	
3	IR reflow		250℃,5sec.Max	
4	Manual soldering	IEC-68-2-20	Not applicable	

#### 2.5 Environmental Characteristics.

No	Items	Standard	Descriptions	
1	Operation temperature		-40℃~+85℃	
2	Operating humidity		10%~95%RH	
3	Storage temperature		-40℃~+85℃	
4	Storage humidity		10%~95%RH	
5	Thermal shock		-40℃~+85℃,5 cycles	
6	Damp heat		40℃,90%RH,10days	
7	Salt-mist		35℃,5% NaCl,24HR	

#### 3 · INTERFACE

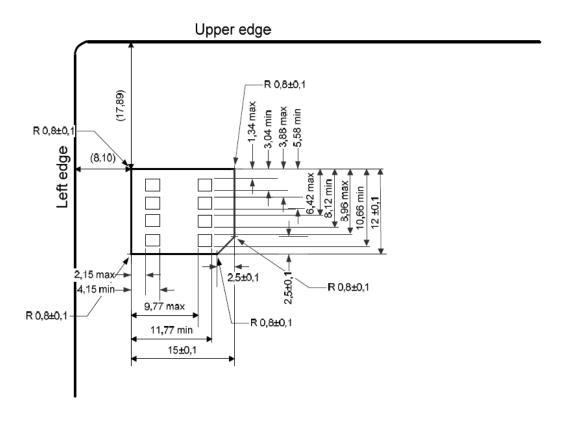
### 3.1 Signals

Sigal interface connections for C790 are shown below.

Contact No	Assignment	Description	Remark
C1	Vcc	Power Voltage	
C2	RST	Reset Signal	
C3	CLK	Clocking Signal	
C4	RFU	Reserve for feature use	
C5	GND	Power and Signal Ground	
C6	Vpp	Programming Voltage	
С7	I/O	Serial Data input/output	
C8	RFU	Reserve for feature use	

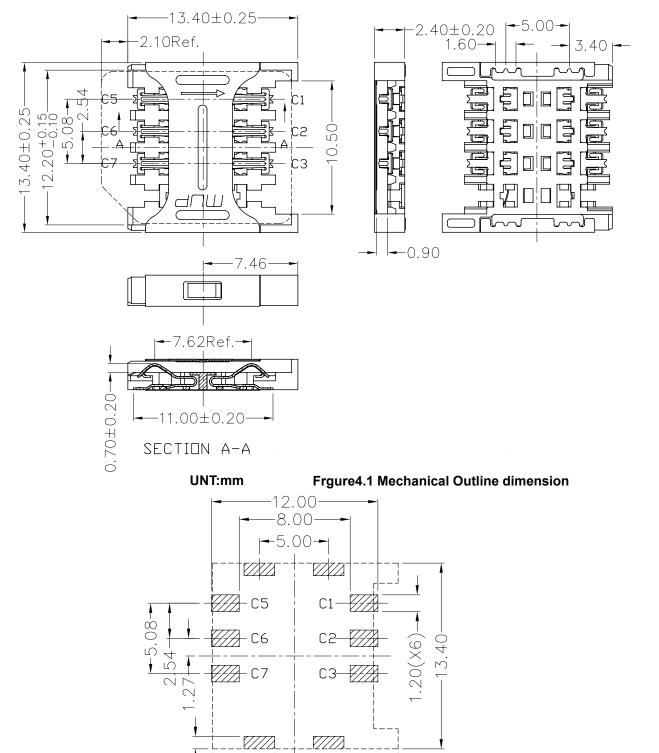
#### 3.2 MicroSIM Card Contact Location(ETSI TS 102 221)

Dimensions in millimeter(mm)



Thickness:0.76±0.08mm

#### 4 MECHANICAL OUTLINE DRAWING



RECOMMENDED P.C.B LAYOUT COMPONENT SIDE(TOLERANCE ±0.05)

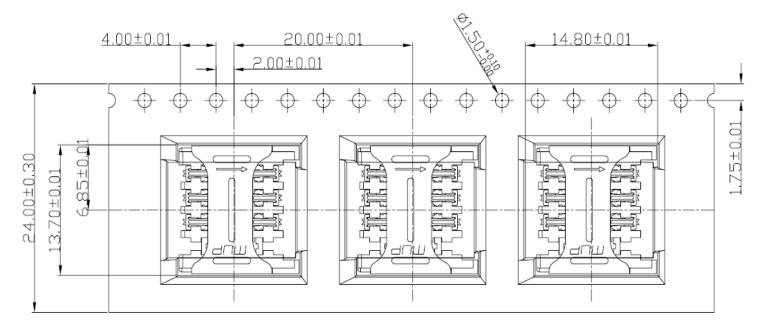
-13.40-

2.20(X4)

7.46-

#### 6. Embossed Tape Carrier Diagram

#### 6.1 Carrier Dimensions Diagram



#### 6.2 Reel Form Diagram

